

Standard Product Reference Sheet

BRGB1315C-TF



Features

Package	3in1 Top Viewing type Out dimension 2.1 × 1.65 × 0.4mm (LxWxH)
Product features	RGB tri-color emitting LEDLead-free soldering compatibleRoHS compliant

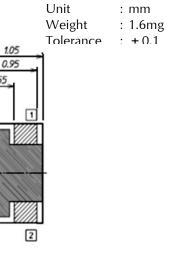
Recommended Applications

Cellular Phone, Home Appliances, Amusement Equipment, Other General Applications

1.65



BRGB1315C-TF



<u>u</u>	ED Chip (2) 2 Green LED Chip (1) Red	Cathode Mark (Green)	<u>39</u> / ∖ ② ③
SYMBOL	PART NAME	MATERIALS	QTY.
1	LED Die	AlGaInP,InGaN	3
2	Lens	Epoxy Resin	1

Glass Fabrics

Au/Ni/Cu

0.55

0.55

LED (2) Green 1	3	LED (3) Blue 5	
Ŷ Ţ	Ŷ	Ŷ V	1 3 5 : Anode
\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	0,	0,	2 4 6: Cathode
2	4	6	
	ED (1 Red)	
	Reu		
Insi	de ci	ircuit	

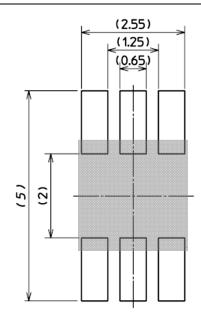
Recommended Pad

Substrate

Terminal

3

4



0.4 +0.07

1

6

0.1 ±0.05

0.95

6

4

Pin Connection

Unit: mm

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[Product Overview]

	LED Die (1)	LED Die (2)	LED Die (3)
Material	AlGalnP	InGaN	InGaN
Emitting Color	RED GREEN BLUE		
Lens Color	MILKY WHITE		

【 Absolute Maximum Ratings 】

(Ta=25)

IT	ГЕМ	SYMBOL	LED Die (1)	LED Die (2)	LED Die (3)	UNITS
Power I	Dissipation	P_d	81	74	58	mW
Total Value of	Power Dissipation	$P_{\rm d}$		150 ※1		mW
Forward Currer	nt (1 chip emitting)	I _F	30	20	15	mA
	rd Current nips emitting)	I _F	17	15	10	mA
Repetitive Peal	k Forward Current	I _{FRM}	100	100	100	mA
Current Derate Linearly	DC (1 chip emitting)	ΔI _F	0.40	0.25	0.18	mA/°C
Linearry	DC (2 or 3 chips emitting)	ΔIF	0.20	0.18	0.12	mA/°C
Derate Linearly From 25°C	Pulse (1 chip emitting)	ΔI _{FRM}	1	1	1	mA/°C
Revers	e Voltage	V _R	5	5	5	V
Operating	Temperature	T _{opr}		−40 ~ +85		°C
Storage 7	emperature	T_{stg}	−40 ~ +100		°C	

Notes

- Forward Current should not exceed Max. Total Value of Power Dissipation (3 chips emitting).
 See technical data for Total Value of Power Dissipation at 25 or more.
- 2. IFRM Conditions: Pulse width 1ms, Duty 1/20

2

Specifications BRGB1315C-TF

[Electro-Optical Characteristics]

L	ED Die (1) RED						(Ta=25)
	ITEM	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNITS
	Forward Voltage	V_{F}	I _F = 5mA	_	1.90	2.50	V
	Reverse Current	I _R	$V_R = 5V$	_	_	100	μΑ
	Luminous Intensity	I_V	I _F = 5mA	17	35	ı	mcd
	Dominant Wavelength	λd	I _F = 5mA	615	_	635	nm
	Spectral line Half Width	Δλ	I _F = 5mA	_	15	_	nm

LED Die (2) GREEN (Ta=25) ITEM **SYMBOL CONDITIONS** TYP. MAX. UNITS MIN. Forward Voltage $V_{\text{F}} \\$ $I_F = 5 \text{mA}$ 3.10 3.50 V Reverse Current 100 $V_R = 5V$ μΑ I_R Luminous Intensity I_V $I_F = 5 \text{mA}$ 95 55 mcd Dominant Wavelength λd $I_F = 5mA$ 515 550 nm Spectral line Half Width $\Delta \lambda$ $I_F = 5mA$ 35 nm

LED Die (3) **BLUE**| ITEM | SYMBOL | CONDITIONS | MIN. | TYP. | MAX. | UNITS |

ITEM	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNITS
Forward Voltage	V _F	I _F = 5mA	1	3.05	3.45	V
Reverse Current	I _R	$V_R = 5V$	1	-	100	μΑ
Luminous Intensity	I_V	I _F = 5mA	12	24	-	mcd
Dominant Wavelength	λd	I _F = 5mA	460	_	480	nm
Spectral line Half Width	Δλ	I _F = 5mA	_	25	_	nm

Above Luminous Intensity (Iv) values and Dominant Wavelength (λd) values are the setup value of the selection machine.

[Tolerance : $lv = \pm 10\%$, $\lambda d = \pm 2 nm$]





[Sorting Chart for Luminous Intensity and Dominant Wavelength]

LEDs shall be sorted out into the following chart.

Conditions : Ta=25°C, $I_F=5$ mA

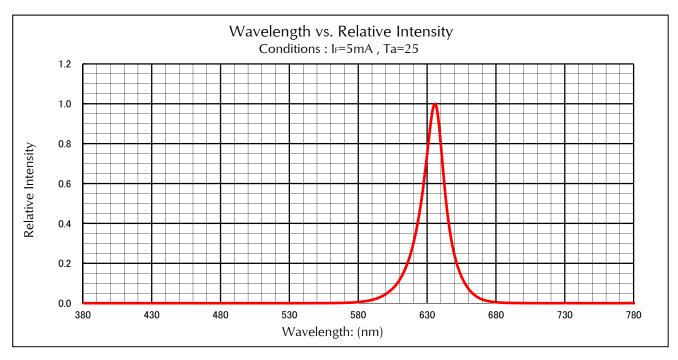
David	Luminous Intensity Iv (mcd)			
Rank	LED Chip (1) RED	LED Chip (2) GREEN	LED Chip (3) BLUE	
Α		55 ~ 95	12~24	
В	17~35	55~95	24~	
С		95∼	12~24	
D		55 57	24~	
Е		55 ~ 95	12~24	
F	0.5	55.295	24~	
G	35∼	95∼	12~24	
Н		95~	24~	

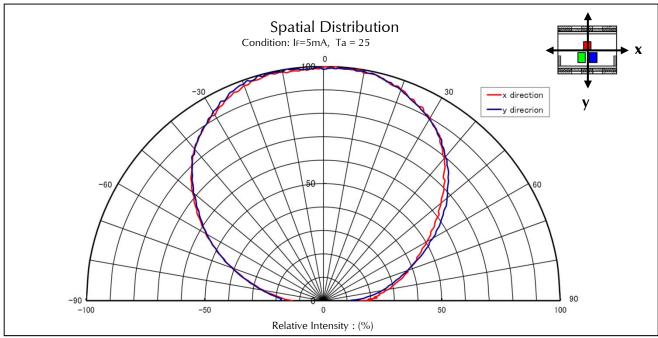
	Conditions :Ta=25°C,I _F =5mA				
Б	Do	minant Wavelen; λ d (nm)	gth		
Rank	LED Chip (1) RED	LED Chip (2) GREEN	LED Chip (3) BLUE		
А	615 - 625	515 - 550	460~470		
В	615~635	515 ~ 550	470 ~ 480		

Above Luminous Intensity (Iv) values and Dominant Wavelength (λd) values are the setup value of the selection machine.

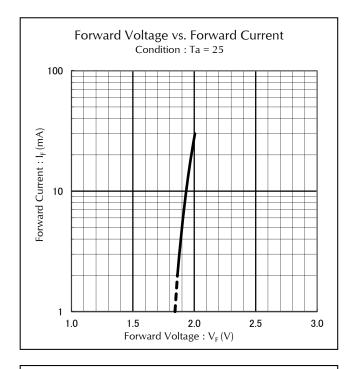
[Tolerance : $Iv = \pm 10\%$, $\lambda d = \pm 2nm$]

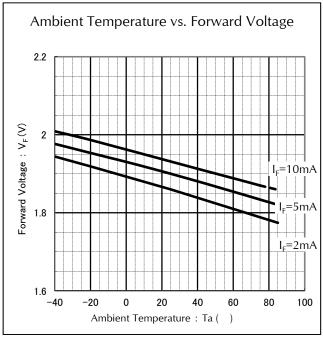


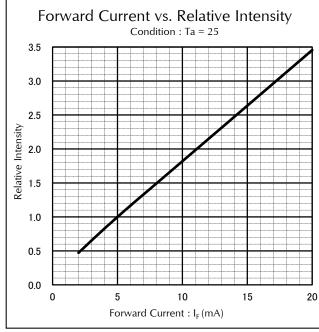


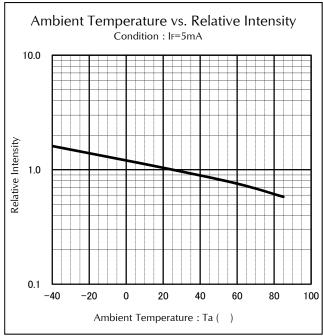




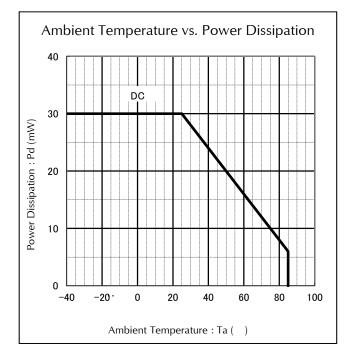


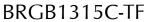


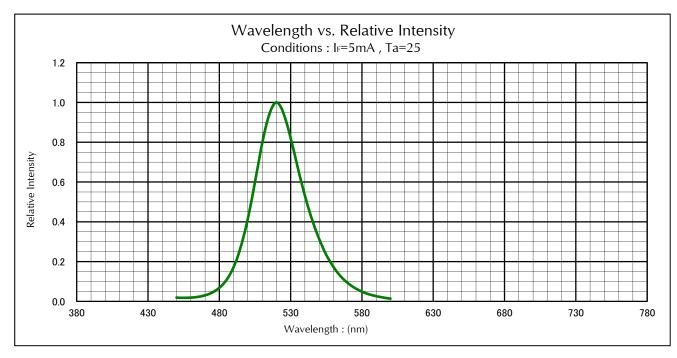


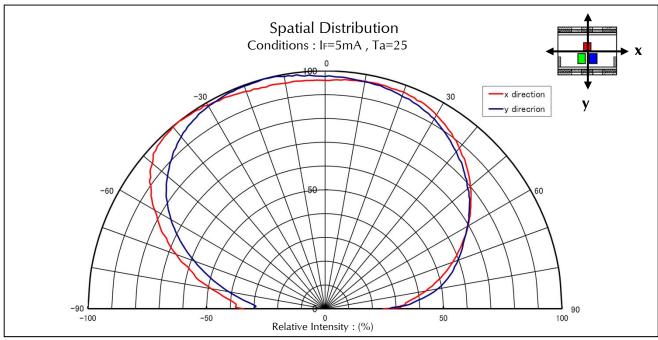


Technical Data(LED Die 1: RED)

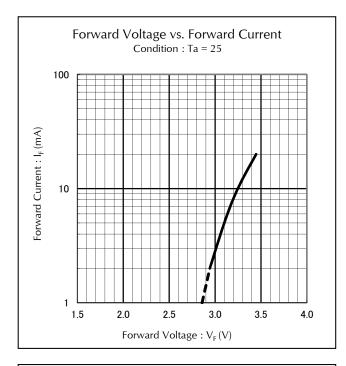


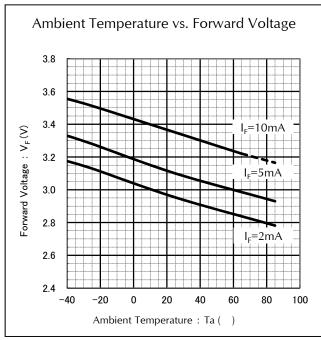


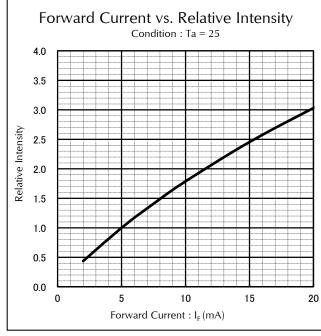


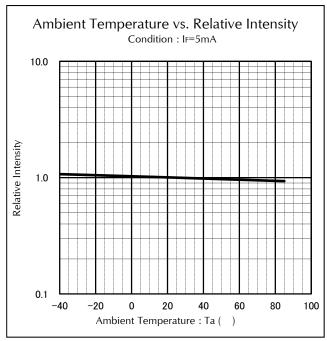


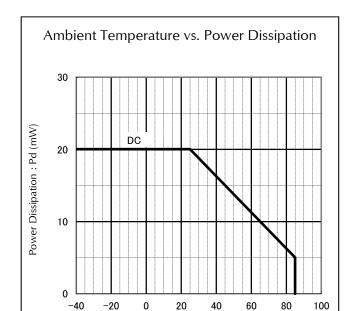




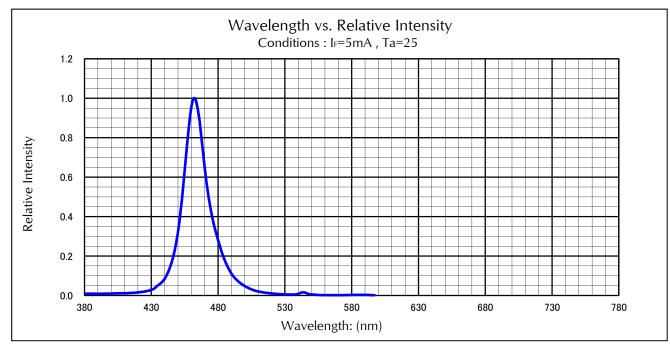


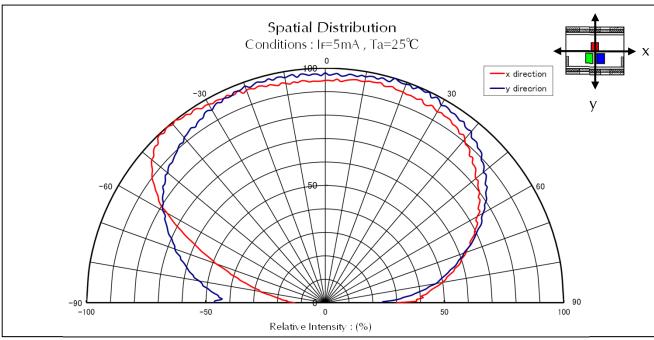


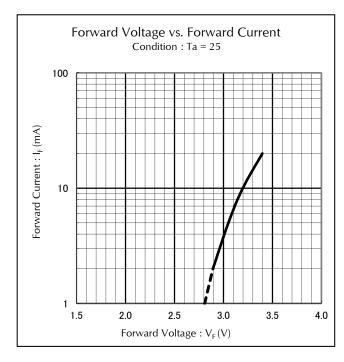


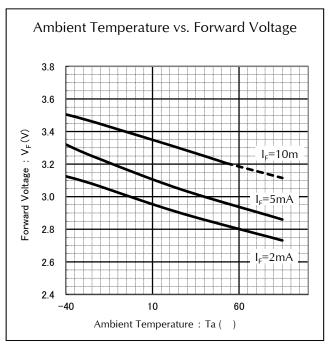


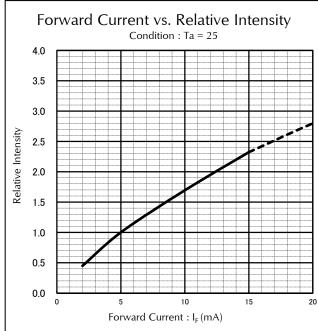
Ambient Temperature : Ta ()

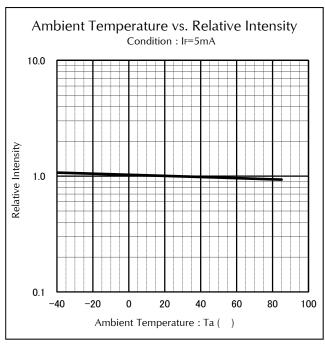


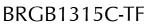


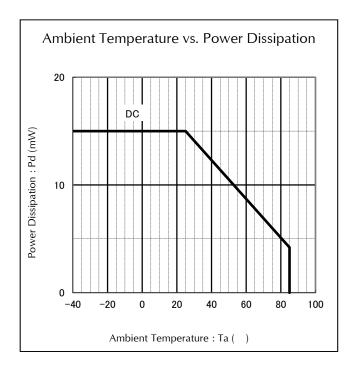










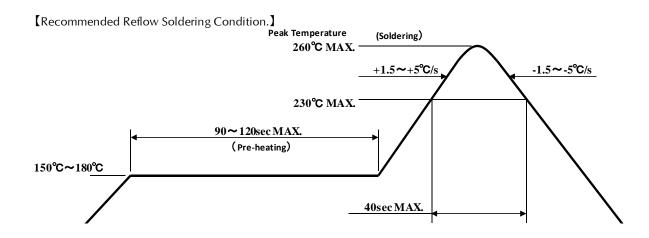


[Soldering Precaution**]**

(acc.to EIAJ-4701/300)

- 1. Heat stress during soldering will influence the reliability of LEDs, however that effect will vary with heating method. Also, if components with different shapes need to be mounted together, it is recommended to set the soldering pad temperature according to the component most vulnerable to heat stress (ex. SMT LED). (Recommended Condition: Soldering Pad temp. > Package temp.)
- 2. LED parts including the resin are not stable immediately after soldering (when they are not at room temperature), any mechanical stress may cause damage to the product. Please avoid such stress after soldering, especially stacking of the boards which may cause the boards to warp and any other types of friction with hard materials.).
- 3. Recommended temperature profile for the Reflow soldering is listed as the temperature of the resin surface. Temperature distribution varies on heating method, PCB material, other components in the assembly, and mounting density.

Please do not repeat the heating process in Reflow process more than twice.



Note 1 Recommended temperature profile for the reflow soldering is listed as the temperature of the resin surface. This should be the maximum temperature for soldering. Lowering the heating temperature and decreasing heating time is very effective in achieving higher reliability.

Note 2 The reflow soldering process should be done up to twice(2 times Max). When second process is performed, interval between first and second process should be as short as possible to prevent absorption of moisture to resin of LED. The second soldering process should not be done until LEDs have returned to room temperature (by nature-cooling) after first soldering process.



Soldering conditions

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- 4. If soldering manually, Stanley recommends using a soldering iron equipped with temperature control. During the actual soldering process, make sure that the soldering iron never touches the LED itself, and avoid the LED's electrode heating temperature reaching above the heating temperature of the solder pad. All repairs must be performed only once in the same spot, and please avoid reusing components.
- 5. In soldering process, immediately after iron tip is cleaned, please make sure that the soldering iron reaches the appropriate temperature, before using. Also, please avoid applying any types of pressure to the soldered components before the solder has been cooled and hardened, as it may deteriorate solder performance and solder quality.

[Recommended Manual Soldering Condition.]

Temperature of Iron Tip	350 MAX.
Soldering Duration, Time	3sec.Max.,1 time

- 6. When using adhesive material for tentative fixatives, thermosetting resin or Ultraviolet radiation (UV) setting resin with heat shall be recommended. 《The curing condition, Temperature:150 Max./Time:120sec.Max.》
- 7. Flow soldering (dip soldering) is not recommended for this product.
- 8. Isopropyl alcohol is recommended for cleaning. Some chemicals, including Freon substitute detergent could corrode the lens or the casing surface, which cause discoloration, cloud, crack and so on. Please review the reference chart below for cleaning. If water is used to clean (including the final cleaning process), please use pure water (not tap water), and completely dry the component before using.

Chemical	Adaptability
Isopropyl Alcohol	0
Trichloroethylene	×
Chlorothene	×
Acetone	×
Thinner	×

Handling Precaution

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【For Electric Static Discharge (ESD)】

ensuring product quality during shipment.

This kind of LED lamp is highly sensitive to surge voltage generated by the On/Off status change and discharges of static electricity through frictions with synthetic materials, which may cause severe damage to the die or undermine its reliability. Damaged products may experience conditions such as extremely high reverse voltage, or a decrease of forward rise voltage, deteriorating its optical characteristic. Stanley products are designed to withstand up to 1,000V under the EIAJ ED-4701/300 Test #304 (HBM), and are packed with anti-static components. However, the following precautions and measures are vital in

EIAJ ED-4701/300 (304/HBM) Electrification model: C=100pF, R2=1.5K Ω

1. Electrification/Static Electricity protection

Stanley recommends the following precautions in order to avoid product (die) damage from static electricity, when an operator and other materials electrified by friction coming in contact with the product.

- ①Do not place electrified non-conductive materials near the LED product.

 Avoid LED products from coming into contact with metallic materials.(Should the metallic material be electrified, the sudden surge voltage will most likely damage the product.)
- ②Avoid a working process which may cause the LED product to rub against other materials.
- ③Install ground wires for any equipment, where they can be installed, with measures to avoid static electricity surges.
- **(4)** Prepare a ESD protective area by placing a Conductive Mattress (1M Ω MAX.) and Ionizer to remove any static electricity.
- ⑤Operators should wear a protective wrist-strap.
- 6 Operators should wear conductive work-clothes and shoes.
- To handle the products directly, Stanley recommends the use of ceramic, and not metallic, tweezers.

2. Working Environment

- ①A dry environment is more likely to cause static electricity. Although a dry environment is ideal for storage state of LED products, Stanley recommends an environment with approximately 50% humidity after the soldering process.
- ②Recommended static electricity level in the working environment is 150V, which is the same value as Integrated Circuits (which are sensitive to static electricity).



Handling Precaution

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[Other Precautions]

- 1. Stanley LED Lamps have semiconductor characteristics and are designed to ensure high reliability. However, the performance may vary depending on usage conditions
- 2. Absolute Maximum Ratings are set to prevent LED lamps from failing due to excess stress(temperature, current, voltage, etc.). Usage conditions must not exceed the ratings for a moment, nor do reach one item of absolute maximum rating s simultaneously.
- 3. In order to ensure high reliability from LED Lamps, variable factors that arise in actual usage conditions should be taken into account for designing. (Derating of TYP., MAX Forward Voltage, etc.)
- 4. Please insert Protective Resistors into the circuit in order to stabilize LED operation and to prevent the device from igniting due to excess current.
- 5. Please check the actual performance in the assembly because the Specification Sheets are described for LED device only.
- 6. Please refrain from looking directly at the light source of LED at high output, as it may harm your vision.
- 7. The products are designed to operate without failure in recommended usage conditions. However, please take the necessary precautions to prevent fire, injury, and other damages should any malfunction or failure arise.
- 8. The products are manufactured to be used for ordinary electronic equipment. Please contact our sales staff beforehand when exceptional quality and reliability are required, and the failure or malfunction of the products might directly jeopardize life or health (such as for airplanes, aerospace, transport equipment, medical applications, nuclear reactor control systems and so on).
- 9. When there is a process of supersonic wave welding etc. after mounting the product, there is a possibility of affecting on the reliability of junction part in package (junction part of die bonding and wire bonding). Please make sure there is no problem before using.
- 10. The formal specification sheets shall be valid only by exchange of documents signed by both parties



Packaging Specifications

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This product is baked (moisture removal) before packaging, and is shipped in moisture-proof packaging (as shown below) to minimize moisture absorption during transportation and storage. However, with regard to storing the products, Stanley recommends the use of dry-box under the following conditions is recommended. Moisture-proof bag as the packaging is made of anti-static material but packaging box is not.

【Recommended Storage Condition / Products Warranty Period 】

Temperature	+5 ~ 30
Humidity	Under 70%

In the case of the package unopened, 6 months under [Recommended Storage Condition]. Please avoid rapid transition from low temp. condition to high temp. condition and storage in corroding and dusty environment.

[Time elapsed after Package Opening.]

The package should not be opened until immediately prior to its use, and please keep the time frame between package opening and soldering which is [maximum 72h].

If the device needs to be soldered twice, both soldering operations must be completed within the 72h.

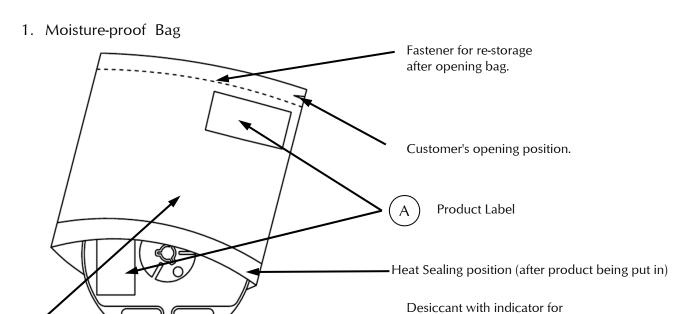
If any components should remain unused, please reseal the package and store them under the conditions described in the [Recommended Storage Condition] above.

This product must be required to perform baking process (moisture removal) for at 23h(MIN.).~72h(MAX.) at 60 ± 5 degrees Celsius if following conditions apply.

- 1. In the case of silica gel (blue) which indicates the moisture level within the package, changes or loses its blue color.
- 2. In the case of time passes for 72h after the package is opened once.

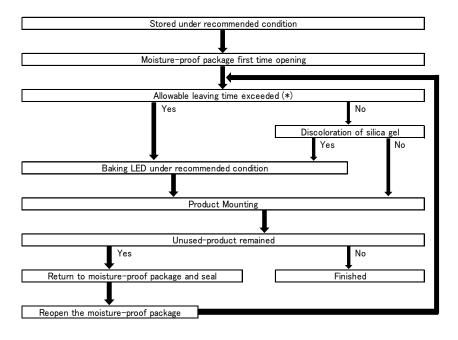
Baking process should be performed after LED having been taken out of the package.

Baking may be performed in the tape-reel form, however if it is performed with the reel stacked over one another, it may cause deformation of the reels and taping materials and later obstruct mounting. Please handle only once it has returned to room temperature. Provided that, baking process shall be 2 times MAX.



SYMBOL	PART NAME	MATERIALS	REMARKS
1	Moisture-proof bag with Aluminum layer	PET+Al+PE	with ESD protection

[Flow Chart-package Opening to Mounting]



Allowable leaving time means the maximum allowable leaving time after opening package, which depends on each LED type.

moisture level is enclosed.

The allowable leaving time should be calculated form the first opening of package to the time when soldering process is finished.

When judging if the allowable leaving time has exceeded or not, please subtract the soldering time. The allowable leaving time after reopening should be calculated form the first opening of package, or from the time when baking process is finished.





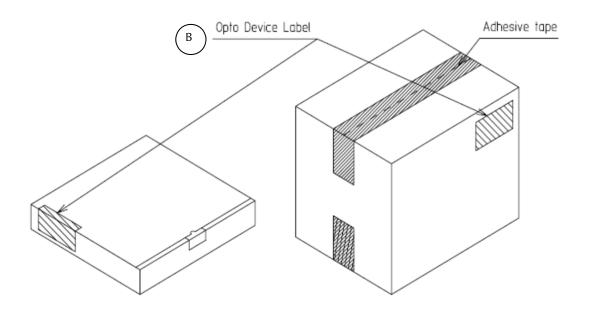
【 Packing box 】

(RoHS•ELV Compliant)

Box TYPE	Outline dimension L \times W \times H (mm)	Capacity of the box
Type A	280 × 265 × 45	3 reels
Type B	310 × 235 × 265	15 reels
Type C	440 × 310 × 265	30 reels

The above measure is all the reference value.

The box is selected out of the above table, by shipping quantity.



Type A

 $Material\ /\ box\ :\ Cardboard\ C5BF$

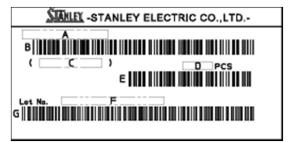
Type B,C

Material / box : Cardboard K5BF Partition : Cardboard K5BF

[Label Specification]

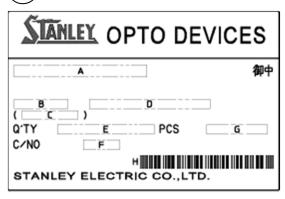
(acc.to JIS-X0503(Code-39))





- A. Parts number
- B. Bar-code for parts number
- C. Parts code (In-house identification code for each parts number)
- D. Packed parts quantity
- E. Bar-Code for packed parts quantity
- F. Lot number & Rank (refer to Lot Number Notational System for details)
- G. Bar-Code for Lot number & Rank

(B) Opto Device Label

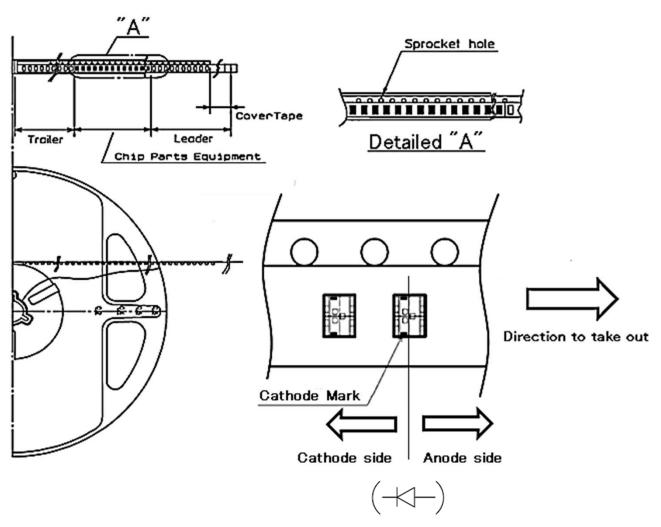


- A. Customer Name
- B. Parts Type
- C. Parts Code
- D. Parts Number
- E. Packed Parts Quantity
- F. Carton Number
- G. Shipping Date
- H. Bar-Code for In-house identification Number

<Remarks> Bar-code font : acc.to Code-39(JIX0503)

(acc.to JIS-C0806)

[Appearance]



Note

"-TR" means Cathode Side of LEDs should be placed on the sprocket-hole side.

Items		Specifications	Remarks	
Cover-tape		Cover-tape shall be longer than 200mm without carrier-tape	The end of cover-tape shall be held with adhesive tape.	
Leader area	Carrier-tape	Empty pocket shall be more than 10pieces.	Please refer to the above figure for Taping & reel orientation.	
Trailer area		Empty pocket shall be more than 15pieces.	The end of taping shall be inserted into a slit of the hub.	

[Qty. per Reel]

4,000 parts/reel (Note1)

Note1 Minimum Qty. per reel might be 1,000 parts when getting less than 4,000 parts. In such case, parts of 1,000-unit-qty. shall be packed in a reel and the qty. shall be identified on the label.

[Mechanical strength]

Cover-tape adhesive strength shall be 0.1~1.0N

(An angle between carrier-tape and cover-tape shall be 170 deg.)

Both tapes shall be so sealed that the contained parts will not come out from the tape when it is bent at a radius of 15mm.

[Others]

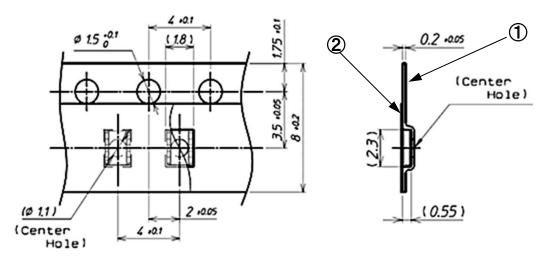
Reversed-orientation, Up-side down placing, side placing and out of spec. parts mix shall not be held. Max qty. of empty pocket per reel shall be defined as follows.

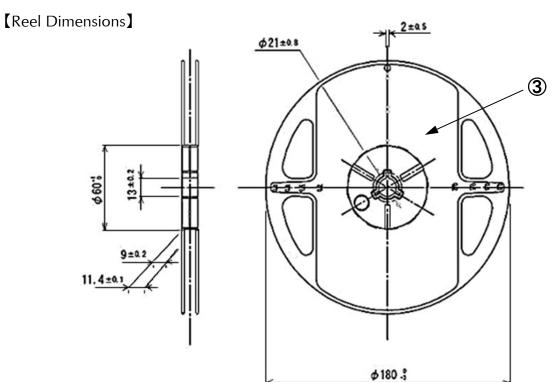
Qty./reel	Max.Qty. of empty pocket	Remarks
1,000	1	-
2,000	2	No continuance
3,000	3	No continuance
4,000	4	No continuance



(acc.to JIS-C0806)

[Taping Dimensions]

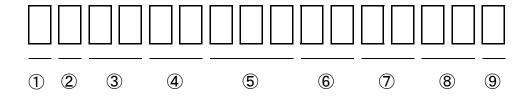




SYMBOL	PART NAME	REMARKS
1	Carrier-tape	Anti-Static Grade
2	Cover-tape	Conductive Grade
3	Carrier-reel	Anti-Static Grade

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① - 1digit: Production Location (Mark identify alphabet)

② - 1digit: Production Year (Last digit of Production Year 2009 9,2010 0,2011 1,···)

③ - 2digits: Production Month (Jan. to Sep., should be 01,02,03,·····)

4 - 2digits: Production Date

⑤ - 3digits: Serial Number

6 - 2digits: Tape and Reel following Number

7 - 2digits: Luminous Intensity Rank.

(If luminous intensity rank is 1 digit, "-" shall be dashed on the place for the second digit. If there is no I identified intensity rank, "--" is used to indicate.)

8 - 2digits: Chromaticity Rank

(If chromaticity rank is 1 digit, "-" shall be dashed on the place for the second digit.

If there is no identified intensity rank, "--" is used to indicate.)

9 - 1digit : Option Rank (Stanley normally print "-" to indicate)

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Correspondence to ELV • RoHS instruction

BRGB1315C-TF

This product is in compliance with RoHS•ELV.

Prohibition substance and it's criteria value of RoHS•ELV are as follows.

- •ELV instruction Refer to following $(1) \sim (4)$.
- •RoHS instruction Refer to following $(1) \sim (6)$.

	Substance Group Name	Criteria Value
(1)	Lead and its compounds	1,000ppm Max
(2)	Cadmium and its compounds	100ppm Max
(3)	Mercury and its compounds	1,000ppm Max
(4)	Hexavalent chromium	1,000ppm Max
(5)	PBB	1,000ppm Max
(6)	PBDE	1,000ppm Max

Reliability Test

Reliability Testing Result

Test Item	Applicable Standard	Test Condition	Duration	Failure
Operating Life	EIAJ ED-4701 /100(101)	Ta=25 I _F =Maximum Rated Current	1,000h	0 / 20
High Temperature Operating Life	EIAJ ED-4701 /100(101)	Ta=85 I _F =Maximum Rated Current(1)	1,000h	0 / 20
Low Temperature Operating Life	EIAJ ED-4701/100(101)	Ta=40 I _F =Maximum Rated Current	1,000h	0 / 20
Wet High Temperature Operating Life	EIAJ ED-4701/100(102)	Ta=60 Rh=90% I _F =Maximum Rated Current	1,000h	0 / 20
Thermal Shock	EIAJ ED-4701/100(105)	Ta= Tstg max. ~ Tstg min. (each 15min)	200cycles	0 / 20
Resistance to Reflow Soldering	EIAJ ED-4701/300(301)	Moisture Soak: 30 70% 72h Preheating: 150~180 90~ 120sec MAX. Soldering: 260 MAX.	twice	0 / 20
Electrostatic Discharge (ESD)	EIAJ ED-4701/300(304)	C=100pF R2=1.5k Ω ±1,000V	once of each polarity	0 / 10

- 1 Maximum Rated Current at Maximum Rated Operating Temperature
- 2 Reference Test

Failure Criteria

ltem	Symbol	Conditions	Failure Criteria
Luminous Intensity	I_{V}	I _F =5mA	Testing Min. Value < Standard Min. Value × 0.5
Forward Voltage	V _F	I _F =5mA	Testing Max. Value ≧ Standard Max. Value × 1.2
Reverse Current	I _R	V _R =5V	Testing Max. Value ≧ Standard Max. Value × 2.5
Cosmetic appearance	-	-	Notable Discoloration, Deformation and Cracking



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